



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2018-08-30
<b>Company Unique ID</b>	NL 008751171B01		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Floriana SAN BIAGIO	<b>Representative Title</b>	AMS MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement		
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>
		Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	KSQ7*U363BDZ	A	SH1A	2018-08-30
Amount	UoM	Unit type	ST ECOPACK Grade	
150	mg	Each	ECOPACK® 2	
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	3.9x9.9x1.25	16	gull wing	
Comment	Q7 SO 16 .15 TO JEDEC MS-012; MDF valid for L6574D013TR			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
;				
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	KSQ7*U363BDZ				5000003.0	1000007.0	
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
Die	M-011 Other inorganic materials	4.886	mg	supplier	die	Silicon (Si)	7440-21-3		4.778	mg	977896	31853	
				supplier	metallization	Aluminium (Al)	7429-90-5		0.007	mg	1433	47	
				supplier	Passivation	Silicon Nitride	12033-89-5		0.031	mg	6345	207	
				supplier	Passivation	Silicon Oxide	7631-86-9		0.043	mg	8801	287	
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.003	mg	614	20	
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.024	mg	4912	160	
Leadframe	M-004 Copper and its alloys	35.844	mg	supplier	alloy	Copper (Cu)	7440-50-8		33.855	mg	944510	225700	
				supplier	alloy	Iron (Fe)	7439-89-6		0.796	mg	22207	5307	
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.048	mg	1339	320	
				supplier	alloy	Zinc (Zn)	7440-66-6		0.042	mg	1172	280	
				supplier	metallization	Nickel (Ni)	7440-02-0		0.086	mg	2399	573	
	supplier	metallization	Palladium (Pd)	7440-05-3		0.003	mg	84	20				
	supplier	metallization	Gold (Au)	7440-57-5		0.004	mg	112	27				
	supplier	metallization	Silver (Ag)	7440-22-4		1.010	mg	28178	6733				
	Die attach	M-015 Other organic materials	1.320	mg	supplier	glue	Silver (Ag)	7440-22-4		1.160	mg	878788	7733
					supplier	glue	Isobornyl Methacrylate	7534-94-3		0.066	mg	50000	440
supplier					glue	Acrylate resin	5888-33-5		0.066	mg	50000	440	
supplier					glue	Methyl acrylate polymer	87320-05-6		0.026	mg	19697	173	
supplier					glue	Epoxyhexyloxyethyltrimethoxysilane	3388-04-3		0.001	mg	758	7	
supplier					glue	Tert-Butyl peroxy(2-ethyl)-hexanoate	3006-82-4		0.001	mg	758	7	
Bonding wires	M-011 Other inorganic materials	0.068	mg	supplier	wire	Copper (Cu)	7440-50-8		0.068	mg	1000000	453	
Encapsulation	M-011 Other inorganic materials	107.883	mg	supplier	mold compound	Silica, vitreous	60676-86-0		94.613	mg	876996	630753	
				supplier	mold compound	Epoxy resin	85954-11-6		4.315	mg	39997	28767	
				supplier	mold compound	Epoxy	29690-82-2		4.315	mg	39997	28767	
				supplier	mold compound	phenol resin	25068-38-6		3.237	mg	30005	21580	
				supplier	mold compound	additive	Proprietary		1.079	mg	10002	7193	
				supplier	mold compound	carbon black	1333-86-4		0.324	mg	3003	2160	